These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable. These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified. These assemblies are ESD sensitive, ESD precautions shall be observed.
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

<table>
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<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: PMP40294</th>
<th>REV: 1.0</th>
<th>SUN REV: Not In VersionControl</th>
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<td>TID #: PMP40294</td>
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PLOT NAME = Bottom Assembly Drawing  GENERATED : 10/30/2017 11:46:58 AM  TEXAS INSTRUMENTS
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